## SN54ABT16374A, SN74ABT16374A 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS <br> SCBS205C - MARCH 1993 - REVISED MAY 1997

- Members of the Texas Instruments Widebus ${ }^{\text {TM }}$ Family
- State-of-the-Art EPIC-IIBTM BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical Volp (Output Ground Bounce) $<0.8 \mathrm{~V}$ at $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$
- High-Impedance State During Power Up and Power Down
- Distributed $V_{C C}$ and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs ( $-32-\mathrm{mA} \mathrm{I}_{\mathrm{OH}}, 64-\mathrm{mA} \mathrm{IOL}^{\text {) }}$
- Package Options Include Plastic 300 -mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and $380-\mathrm{mil}$ Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings


## description

The 'ABT16374A are 16-bit edge-triggered D-type flip-flops with 3 -state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.
A buffered output-enable ( $\overline{\mathrm{OE}}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components
$\overline{\text { OE does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while }}$ the outputs are in the high-impedance state.
When $\mathrm{V}_{\mathrm{Cc}}$ is between 0 and 2.1 V , the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V , $\overline{\mathrm{OE}}$ should be tied to $\mathrm{V}_{\mathrm{CC}}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16374A is characterized for operation over the full military temperature range of $-55^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$. The SN74ABT16374A is characterized for operation from $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

| (each flip-flop) |  |  |  |
| :---: | :---: | :---: | :---: |
| INPUTS |  |  | OUTPUT |
| $\overline{O E}$ | CLK | D | Q |
| $L$ | $\uparrow$ | $H$ | $H$ |
| L | $\uparrow$ | L | L |
| L | $H$ or L | $X$ | $Q_{0}$ |
| $H$ | $X$ | $X$ | $Z$ |

logic symbol $\dagger$

$\dagger$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
logic diagram (positive logic)


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absolute maximum ratings over operating free-air temperature range (unless otherwise noted) $\dagger$



Current into any output in the low state, $\mathrm{I}_{\mathrm{O}}$ : SN54ABT16374A ...................................... 96 mA
SN74ABT16374A ............................................. 128 mA
Input clamp current, $\mathrm{I}_{\mathrm{IK}}\left(\mathrm{V}_{\mathrm{I}}<0\right)$....................................................................... -18 mA

Package thermal impedance, $\theta_{\mathrm{JA}}$ (see Note 2): DGG package . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . $89^{\circ} \mathrm{C} / \mathrm{W}$
DL package ............................................ $94^{\circ} \mathrm{C} / \mathrm{W}$

$\dagger$ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.
recommended operating conditions (see Note 3)

|  |  |  | SN54ABT16374A |  | SN74ABT16374A |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | MAX | MIN | MAX |  |
| $\mathrm{V}_{\mathrm{CC}}$ | Supply voltage |  | 4.5 | 5.5 | 4.5 | 5.5 | V |
| $\mathrm{V}_{\mathrm{IH}}$ | High-level input voltage |  | 2 |  | 2 |  | V |
| $\mathrm{V}_{\mathrm{IL}}$ | Low-level input voltage |  |  | 0.8 |  | 0.8 | V |
| $\mathrm{V}_{1}$ | Input voltage |  | 0 | $\mathrm{V}_{\mathrm{CC}}$ | 0 | $\mathrm{V}_{\mathrm{CC}}$ | V |
| ${ }^{\mathrm{O}} \mathrm{OH}$ | High-level output current |  |  | -24 |  | -32 | mA |
| $\mathrm{I}_{\mathrm{OL}}$ | Low-level output current |  |  | 48 |  | 64 | mA |
| $\Delta t / \Delta v$ | Input transition rise or fall rate | Outputs enabled |  | 10 |  | 10 | $\mathrm{ns} / \mathrm{V}$ |
| $\Delta t / \Delta V_{C C}$ | Power-up ramp rate |  | 200 |  | 200 |  | $\mu \mathrm{s} / \mathrm{V}$ |
| $\mathrm{T}_{\mathrm{A}}$ | Operating free-air temperature |  | -55 | 125 | -40 | 85 | ${ }^{\circ} \mathrm{C}$ |

NOTE 3: Unused inputs must be held high or low to prevent them from floating.
electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)


* On products compliant to MIL-PRF-38535, this parameter does not apply.
$\dagger$ All typical values are at $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}$.
$\ddagger$ This parameter is characterized, but not production tested.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
I This is the increase in supply current for each input that is at the specified TTL voltage level rather than $V_{C C}$ or GND.
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)


[^0]switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN54ABT16374A |  |  |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | $\begin{aligned} & \mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \\ & \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C} \end{aligned}$ |  |  | MIN | MAX |  |
|  |  |  | MIN | TYP | MAX |  |  |  |
| $\mathrm{f}_{\text {max }}$ |  |  | 150 |  |  | 150 |  | MHz |
| tPLH | CLK | Q | 1.8 | 4.3 | 5.7 | 1.5 | 6.9 | ns |
| tPHL |  |  | 2.7 | 4.7 | 6.1 | 2.2 | 6.9 |  |
| tPZH | $\overline{\mathrm{OE}}$ | Q | 1.2 | 3.4 | 4.8 | 0.8 | 6.1 | ns |
| tPZL |  |  | 1.6 | 3.5 | 4.9 | 1.2 | 5.5 |  |
| tPHZ | $\overline{\mathrm{OE}}$ | Q | 2.2 | 5.5 | 8.6 | 1.8 | 9.6 | ns |
| tPLZ |  |  | 2.2 | 4.3 | 6.2 | 1.8 | 7.2 |  |

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN74ABT16374A |  |  |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | $\begin{aligned} & \hline \mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \\ & \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C} \end{aligned}$ |  |  | MIN | MAX |  |
|  |  |  | MIN | TYP | MAX |  |  |  |
| $f_{\text {max }}$ |  |  | 150 |  |  | 150 |  | MHz |
| tPLH | CLK | Q | 1.8 | 4.3 | 5.4 | 1.8 | 6.2 | ns |
| tPHL |  |  | 2.7 | 4.7 | 5.6 | 2.7 | 5.9 |  |
| tPZH | $\overline{\mathrm{OE}}$ | Q | 1.2 | 3.4 | 4.8 | 1.2 | 5.6 | ns |
| tPZL |  |  | 1.6 | 3.5 | 4.7 | 1.6 | 5.3 |  |
| tPHZ | $\overline{\mathrm{OE}}$ | Q | 2.2 | 5.5 | 7.1 | 2.2 | 8.2 | ns |
| tPLZ |  |  | 2.2 | 4.3 | 5.8 | 2.2 | 6.6 |  |

## PARAMETER MEASUREMENT INFORMATION



| TEST | S1 |
| :---: | :---: |
| $\mathrm{t}^{\mathrm{TLH}} / \mathrm{t}_{\mathrm{PHL}}$ | Open |
| $\mathrm{t}^{\mathbf{P L Z}} / \mathrm{t}_{\mathrm{PZL}}$ | 7 V |
| $\mathrm{t}_{\mathrm{PHZ}} / \mathrm{t}_{\mathrm{PZH}}$ | Open |


VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS

## PACKAGING INFORMATION

| Orderable Device | Status ${ }^{(1)}$ | Package <br> Type | Package <br> Drawing | Pins Package <br> Qty | Eco Plan ${ }^{(2)}$ | Lead/Ball Finish | MSL Peak Temp ${ }^{(3)}$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 5962-9320101MXA | ACTIVE | CFP | WD | 48 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 74ABT16374ADGGRE4 | ACTIVE | TSSOP | DGG | 48 | 2000 | Pb-Free <br> (RoHS) | CU NIPDAU | Level-1-250C-UNLIM |
| SN74ABT16374ADGGR | ACTIVE | TSSOP | DGG | 48 | 2000 | Pb-Free <br> (RoHS) | CU NIPDAU | Level-1-250C-UNLIM |
| SN74ABT16374ADL | ACTIVE | SSOP | DL | 48 | 25 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ABT16374ADLR | ACTIVE | SSOP | DL | 48 | 1000 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ABT16374ADLRG4 | ACTIVE | SSOP | DL | 48 | 1000 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SNJ54ABT16374AWD | ACTIVE | CFP | WD | 48 | 1 | TBD | Call TI | Level-NC-NC-NC |

${ }^{(1)}$ The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but Tl does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.
${ }^{(2)}$ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS \& no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb -Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed $0.1 \%$ by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb -Free products are suitable for use in specified lead-free processes.
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${ }^{(3)}$ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only
E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB


| PIM | $\mathbf{2 8}$ | $\mathbf{4 8}$ | $\mathbf{5 6}$ |
| :---: | :---: | :---: | :---: |
| A MAX | 0.380 <br> $(9,65)$ | 0.630 <br> $(16,00)$ | 0.730 <br> $(18,54)$ |
| A MIN | 0.370 <br> $(9,40)$ | 0.620 <br> $(15,75)$ | 0.720 <br> $(18,29)$ |

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed $0.006(0,15)$.
D. Falls within JEDEC MO-118

48 PINS SHOWN


NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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[^0]:    \# These values apply only to the SN74ABT16374A.

